

AMENDMENTS TO THE SPECIFICATION

Please amend the following paragraphs in the specification:

[0022] FIGS. 12A and 12B are cross-sectional views of ~~alternative~~ **various embodiments** of semiconductor packages formed **through the use of leadframes constructed** according to ~~an embodiment of~~ the **present** invention.

[0062] FIG. ~~12~~ **12A** is a sectional diagram of an exemplary semiconductor package 1400 that includes leadframe 120 of FIG 2A. Practitioners will appreciate that a wide variety of leadframes can be made in view of the teachings herein, and that a wide variety of packages can be made with such leadframes. Accordingly, package ~~400~~ **1400** is just an example.

[0066] Leadframes 130 and 140 of FIGS. 4A and 5, respectively, may be provided in packages similar to package 1400 of FIG. ~~12~~ **12A** . In a package 1410 made with leadframe **130 or** 140, as shown in FIG. ~~12A~~ **12B**, the semiconductor chip 1402 is mounted one inner end segments 200a, 202a in a flip chip style using solder balls 1412.